

REMARKS

This is in response to the Office Action dated February 13, 2003. In view of the foregoing amendments and following representations, reconsideration is respectfully requested.

In the previous Office Action, claims 31-36 were allowed, and claims 26-30 were rejected under 35 U.S.C. 102(e) as being anticipated by Grabbe (U.S. Patent No. 5,637,919). It is submitted that the present invention, as embodied by claims 26-30, is allowable over the Grabbe reference for the following reasons.

The present invention, as defined in claim 26, requires at least one recognition mark, located on a surface of an electronic component, for serving as a reference for the arrangement positions of the electrical connecting portions. Thus, even though the electrical connecting portions are shifted relative to the electronic component, the electrical connecting portions are shifted on the basis of the recognition mark, so that the shifted amount of the recognition mark is the same as that of the electrical connecting portions. Therefore, if the position of the recognition mark is detected by a component inspecting section (recognition device), the positions of the electrical connecting portions can be accurately detected.

In contrast, the **Grabbe** reference merely discloses a semiconductor chip 10 having a large and small diameter projections 46, 48, which are formed on the bottom of the chip and can be received in cylindrical recesses 50, 52 to assure that the contact sites 20

correspond to the contact points of the connection members 18. With this arrangement, the electrodes of the chip will agree with the lands on the board. In other words, Grabbe fails to teach or suggest at least one recognition mark, which serves as a reference for the arrangement positions of the electrical connecting portions. The recognition mark is located on a surface of the electronic component.

Further, in Grabbe, since the component is positioned and mechanically regulated on the board by a mechanical mechanism, the positioning accuracy becomes rough so that it is difficult to meet a recently required accuracy in a case where the pitch between the electrodes is on the order of 0.3 mm or less. In addition, when the positions of the recesses are shifted, the component will be mounted at the shifted position, and thus the recess cannot serve as a reference for the electrical connecting portions.

In the present invention, when the recognition mark is recognized and the recognized position is corrected, a component can be mounted so that the electrical connecting portions accurately agree with the connecting portions on the board in order to provide the accuracy that is necessary for the above fine pitch requirement.

Accordingly, it is submitted that the Grabbe clearly does not disclose a recognition mark located on a surface of an electronic component and serving as a reference for the arrangement position of the electrical connecting portions.

In view of the above, it is submitted that the present application is now clearly in condition for allowance. The Examiner therefore is requested to pass this case to issue.

In the event that the Examiner has any comments or suggestions of a nature necessary to place this case in condition for allowance, then the Examiner is request d to contact Applicant's undersigned attorney by telephone to promptly resolve any remaining matters.

Respectfully submitted,

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